This is a published notice on the Find a Tender service: https://www.find-tender.service.gov.uk/Notice/011643-2021

Not applicable

Metal 3D Printer

COMPOUND SEMICONDUCTOR APPLICATIONS CATAPULT LIMITED

F14: Notice for changes or additional information
Notice identifier: 2021/S 000-011643
Procurement identifier (OCID): ocds-h6vhtk-02ac1f
Published 25 May 2021, 4:37pm

Section I: Contracting authority/entity

I.1) Name and addresses

COMPOUND SEMICONDUCTOR APPLICATIONS CATAPULT LIMITED

Celtic Way Imperial Park

Newport

NP10 8BE

Email

procurement@csa.catapult.org.uk

Country

United Kingdom

NUTS code

UKL - Wales

Internet address(es)

Main address

https://csa.catapult.org.uk

Buyer's address

https://csa.catapult.org.uk

Section II: Object

II.1) Scope of the procurement

II.1.1) Title

Metal 3D Printer

Reference number

ICT-2021-046

II.1.2) Main CPV code

- 38000000 - Laboratory, optical and precision equipments (excl. glasses)

II.1.3) Type of contract

Supplies

II.1.4) Short description

Scope The Compound Semiconductor Applications (CSA) Catapult is looking to create a modular, flexible, accelerated prototype package assembly and test facility for RF, Photonics, and Power compound semiconductor devices, modules and systems. This would allow research, proof of concept and demonstrate its feasibility and small volume prototype build. As part of the electronics package assembly research and development methodology we require a machine that can produce customised prototype metal parts using additive manufacturing technology. This will allow the CSA Catapult to support the Driving the Electric Revolution - Industrialisation Centres (DERIC) programme that is currently active within the UK in developing novel technology for power electronic devices and other types of semiconductor devices. The intention is that the additive manufacturing of bespoke metal components will closely support the requirements of development programmes and further the development of electronic and semiconductor device packaging with novel solutions not currently possible using traditional manufacturing techniques. The equipment will also compliment the hybridisation programmes for packaging that are currently in progress at the CSA Catapult. The equipment shall be

flexible and be able to process several metals compatible with the advanced packaging of electronic devices. These include copper, nickel alloys, and stainless steels. Other materials may be of interest as well due the nature of any developments. The manufacturer/authorised vendor shall install the system at CSA Catapults Innovation Centre, which will be equipped with access to all power and services for full installation and operation and be used to support contract research and development or commercial opportunities within the UK. The manufacturer/authorised vendor is also responsible for providing necessary training, warranty and service/maintenance support System Outline The system architecture is expected to be a standalone machine and is expected to have additional post processing equipment to support the component build. This will include equipment for cleaning, curing and sintering of the parts to produce this final component. It may also include equipment to handle, store and sort the raw material. The system should have capability to be used for both prototype device and low volume production quantities. The system shall be easy to configure and change for the user to allow different processes. A system solution is required that is flexible and upgradeable in the future. Additional module options can then be purchased based on changing industry trends or specific requirements from customers or partners for technology development. The system should also include user software, installation and training. The estimated value of the contract is £250,000 to £350,000 including all options and extensions. The system will be ordered in June and installed in September 2021.

Section VI. Complementary information

VI.6) Original notice reference

Notice number: 2021/S 000-009390

Section VII. Changes

VII.1) Information to be changed or added

VII.2) Other additional information

Scope

The Compound Semiconductor Applications (CSA) Catapult is looking to create a modular, flexible, accelerated prototype package assembly and test facility for RF, Photonics, and Power compound semiconductor devices, modules and systems. This would allow research, proof of concept and demonstrate its feasibility and small volume prototype build.

As part of the electronics package assembly research and development methodology we require a machine that can produce customised prototype metal parts using additive manufacturing technology. This will allow the CSA Catapult to support the Driving the Electric Revolution - Industrialisation Centres (DERIC) programme that is currently active within the UK in developing novel technology for power electronic devices and other types of semiconductor devices. The intention is that the additive manufacturing of bespoke metal components will closely support the requirements of development programmes and further the development of electronic and semiconductor device packaging with novel solutions not currently possible using traditional manufacturing techniques. The equipment will also compliment the hybridisation programmes for packaging that are currently in progress at the CSA Catapult.

The equipment shall be flexible and be able to process several metals compatible with the advanced packaging of electronic devices. These include copper, nickel alloys, and stainless steels. Other materials may be of interest as well due the nature of any developments.

The manufacturer/authorised vendor shall install the system at CSA Catapults Innovation Centre, which will be equipped with access to all power and services for full installation and operation and be used to support contract research and development or commercial opportunities within the UK. The manufacturer/authorised vendor is also responsible for providing necessary training, warranty and service/maintenance support

System Outline

The system architecture is expected to be a standalone machine and is expected to have additional post processing equipment to support the component build. This will include equipment for cleaning, curing and sintering of the parts to produce this final component. It may also include equipment to handle, store and sort the raw material.

The system should have capability to be used for both prototype device and low volume production quantities. The system shall be easy to configure and change for the user to allow different processes.

A system solution is required that is flexible and upgradeable in the future. Additional module options can then be purchased based on changing industry trends or specific requirements from customers or partners for technology development. The system should also include user software, installation and training.

The estimated value of the contract is £450,000 to £550,000 including all options and extensions.

The system will be ordered in June and installed in October 2021.

To express interest in this opportunity and receive the procurement documents, please email procurement@csa.catapult.org.uk with the reference ICT-2021-049 in the subject field.

The deadline for this opportunity is 10am on 8 June 2021.